RECEIVED 30 MAR 1998 REGISTRY OF TRADE MARKS & PATENTS SINGAPORE

9801174-5

RTMP COPY

PCT

WORLD INTELLECTUAL PROPERTY ORGANIZATION
International Bureau

INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification 6 :
H01L 23/28, 23/495, 23/10, 23/34

A1

(11) International Publication Number: WO 97/02600

(43) International Publication Date: 23 January 1997 (23.01.97)

(21) International Application Number: PCT/US96/10982

(22) International Filing Date: 27 June 1996 (27.06.96)

(30) Priority Data:
497,836 3 July 1995 (03.07.95) US

(71) Applicant: OLIN CORPORATION [US/US]; 350 Knotter Drive, P.O. Box 586, Cheshire, CT 06410-0586 (US).

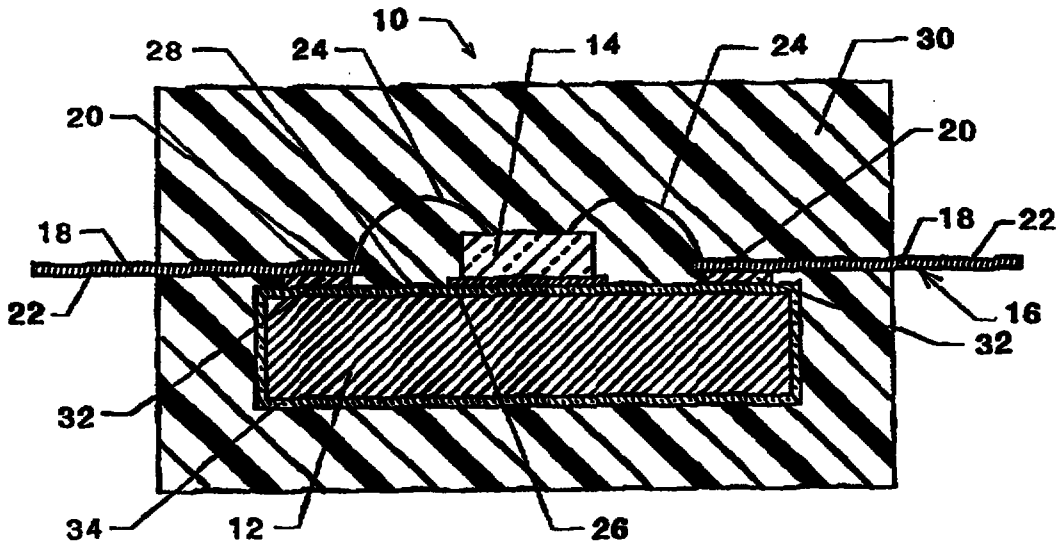
(72) Inventor: PARTHASARATHI, Arvind; 142 Linsley Lake Road, North Branford, CT 06471 (US).

(74) Agents: ROSENBLATT, Gregory, S. et al.; Wiggin & Dana, One Century Tower, New Haven, CT 06508-1832 (US).

(81) Designated States: AL, AM, AT, AU, AZ, BB, BG, BR, BY, CA, CH, CN, CZ, DE, DK, EE, ES, FI, GB, GE, HU, IL, IS, JP, KE, KG, KP, KR, KZ, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, TJ, TM, TR, TT, UA, UG, UZ, VN, Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG).

Published
With international search report.
With amended claims and statement.

(54) Title: ELECTRONIC PACKAGE WITH IMPROVED THERMAL PROPERTIES



(57) Abstract

An electronic package (10) having improved thermal performance. In the case of a plastic (30) package, the inner ends (20) of the leads (18) of the lead frame are attached to a heat slug (12) by a high thermal conductivity material (32) such as solder or a polymeric material. In the case of a metal package, the inner ends of the leads of the lead frame are attached to the metal base component by a high thermal conductivity material.